

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: **Makoto Yoshino, et al.**
Serial No.: **09/909,013**
Filed: **07/19/2001**
For: **Semiconductor Package Insulation Film
And Manufacturing Method Thereof**

Docket No.: **TIJ-29448**
Art Unit: **2829**
Examiner: **Geyer, Scott B.**
Conf. No.: **8724**

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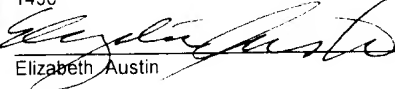
NOTICE OF APPEAL

Commissioner For Patents
Alexandria, VA 22313-1450

Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that the above correspondence is being deposited with the US Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450


Elizabeth Austin

7/8/2003
Date

Applicant hereby appeals to the Board of Appeals from the decision dated April 8, 2003, of the Primary Examiner finally rejecting Claims 5-10, 12, 14, 15, and 17-19.

Charge the fee of \$320.00 to the deposit account of Texas Instruments Incorporated, Account No. 20-0668. An original and two copies of this sheet are enclosed.

Texas Instruments Incorporated
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Respectfully submitted,



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